

50 Ω Wideband 50 to 6000 MHz

TCBT-6G+



Generic photo used for illustration purposes only

CASE STYLE: GU1604

+RoHS Compliant
The +Suffix identifies RoHS Compliance. See our web site for RoHS Compliance methodologies and qualifications



Features

- wideband, 50 to 6000 MHz
- low insertion loss, 0.7 dB typ.
- miniature surface mount 0.15"x0.15"
- protected by US Patent, 7,012,486
- aqueous washable

Applications

- · biasing amplifiers
- biasing of laser diodes
- biasing of active antennas

Electrical Specifications

	Parameter	Frequency (MHz)	Min.	Тур.	Max.	Unit
Frequency Rang	e		50		6000	MHz
		50-500	_	0.2	0.8	
Insertion Loss		500-3000	_	0.7	1.8	dB
		3000-6000	_	1.1	2.5	
		50-500	38	52	_	
Isolation	(RF port to DC port) (RF & DC port to DC port)	500-3000	18	28	_	dB
	(Till & DO port to DO port)	3000-6000	14	19	_	
		50-500	_	1.05	1.5	
VSWR		500-3000	_	1.1	1.3	:1
		3000-6000	_	1.2	2.2	

External C1(0.01 μ F) is required. See functional schematic and PCB layout.

Maximum Ratings

Parameter	Ratings
Operating Temperature	-40°C to 85°C
Storage Temperature	-55°C to 100°C
RF Power	30 dBm max.
Voltage at DC port	25 V max.
DC Current	200mA

Permanent damage may occur if any of these limits are exceeded.

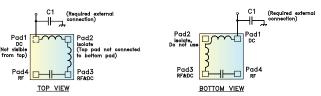
Pad Terminations

Function	Pad Number
RF	4
RF&DC	3
DC	1
ISOLATE (see PCB Layout)	2

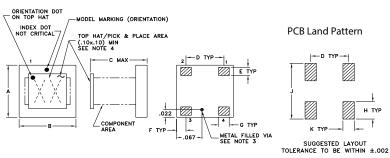
Product Marking



Functional Schematic



Outline Drawing





"TCBT" SERIES MODELS

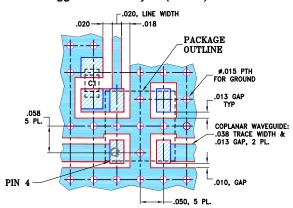
Notes:

- $3. \, \text{Must be isolated from external conductors on mounting surface} \, . \, \, \, \text{Suggested solder mask area is .025} \, x.025.$ At Mini-Circuits option via may be removed.
- 4. Top-Hat total thickness: .013 inches MAX.

Outline Dimensions (inch)

Α	В	С	D	Ε	F
.150	.150	.150	.100	.030	.025
3.81	3.81	3.81	2.54	0.76	0.64
G	Н	J	K		wt
G .028	H .050	J .160	K .030		wt grams

Demo Board MCL P/N: TB-268 Suggested PCB Layout (PL-146)



CAPACITOR C1: .010 uF, 0603 SIZE

NOTES:

- INCLES:

 1. COPLANAR WAVEGUIDE PARAMETERS ARE SHOWN FOR ROGERS RO4350B

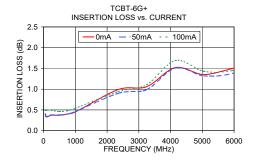
 WITH DIELECTRIC THICKNESS 0.020±0.0015; COPPER: 1/2 0Z. EACH SIDE.

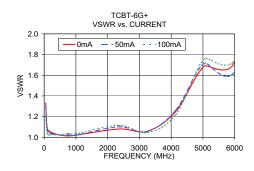
 FOR OTHER MATERIALS TRACE WIDTH AND GAP MAY NEED TO BE MODIFIED.

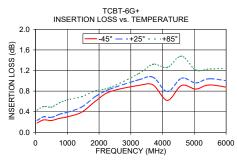
 2. BOTTOM SIDE OF THE PCB IS CONTINUOUS GROUND PLANE.
- DENOTES PCB COPPER LAYOUT WITH SMOBC (SOLDER MASK OVER BARE COPPER).
 - DENOTES COPPER LAND PATTERN FREE OF SOLDER MASK.

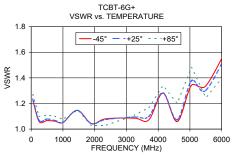
Typical Performance Data

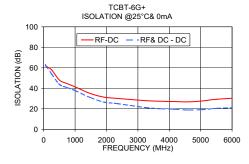
FREQUENCY (MHz)	INSERTION LOSS (dB) with temperature				VSWR (:1) h temperat	ISOLATION (dB) 0mA		
	-45°C	+25°C	+85°C	-45°C	+25°C	+85°C	RF - DC	RF & DC -DC
50.00	0.18	0.23	0.43	1.23	1.24	1.27	62.01	63.14
250.00	0.24	0.30	0.50	1.06	1.07	1.10	58.05	54.10
500.00	0.23	0.29	0.49	1.07	1.08	1.11	48.04	43.88
750.00	0.27	0.35	0.57	1.06	1.07	1.10	44.58	40.67
1000.00	0.30	0.39	0.63	1.05	1.05	1.08	41.47	37.79
1450.00	0.39	0.49	0.69	1.15	1.15	1.15	35.33	31.47
1900.00	0.61	0.70	0.81	1.04	1.04	1.03	31.51	26.67
2350.00	0.79	0.84	0.87	1.08	1.07	1.03	30.13	25.03
3250.00	0.91	1.02	1.14	1.09	1.09	1.11	27.98	21.20
3700.00	0.92	1.07	1.32	1.07	1.10	1.17	27.37	20.10
4150.00	0.62	0.79	1.26	1.28	1.28	1.34	27.10	19.55
4600.00	0.91	1.05	1.48	1.06	1.07	1.20	26.78	18.79
5050.00	0.84	0.96	1.21	1.34	1.38	1.48	27.64	19.18
5500.00	0.92	1.04	1.23	1.34	1.30	1.25	29.30	20.39
6400.00	0.83	0.96	1.25	1.74	1.70	1.51	31.01	21.50











- Additional Notes

 A. Performance and quality attributes and conditions not expressly stated in this specification document are intended to be excluded and do not form a part of this specification document.
- A. Perioritance and quanty attributes and continuous and continuous and expressly stated in it has specification document are based on Mini-Circuit's applicable earlied to the excluded state of the part of this specification document are based on Mini-Circuit's applicable established test performance criteria and measurement instructions.

 C. The parts covered by this specification document are subject to Mini-Circuits standard limited warranty and terms and conditions (collectively, "Standard Terms"); Purchasers of this part are entitled to the rights and benefits contained therein. For a full statement of the Standard Terms and the exclusive rights and remedies thereunder, please visit Mini-Circuits' website at www.minicircuits.com/MCLStore/terms.jsp

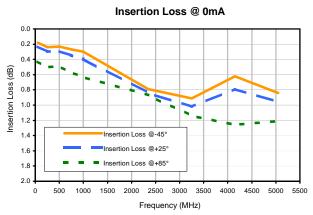


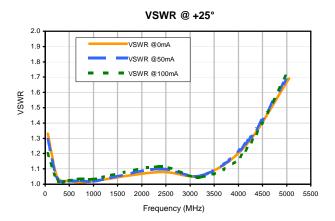
Typical Performance Data

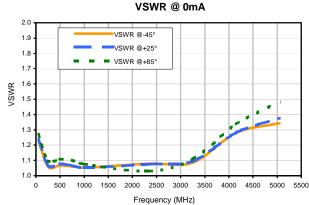
FREQ.		(R	INSERTION LOSS (RF Port to RF&DC Port)						VS	WR		
(MHz)			(d	B)					(:	1)		
		+25°			0mA			+25°			0mA	
	0mA	50mA	100mA	-45°	+25°	+85°	0mA	50mA	100mA	-45°	+25°	+85°
50	0.36	0.41	0.49	0.18	0.23	0.43	1.33	1.29	1.20	1.23	1.24	1.27
250	0.37	0.38	0.49	0.24	0.30	0.50	1.04	1.03	1.03	1.06	1.07	1.10
500	0.37	0.38	0.46	0.23	0.29	0.49	1.02	1.02	1.02	1.07	1.08	1.11
750	0.40	0.40	0.48	0.27	0.35	0.57	1.01	1.02	1.03	1.06	1.07	1.10
1000	0.45	0.46	0.54	0.30	0.39	0.63	1.02	1.02	1.03	1.05	1.05	1.08
2350	0.99	0.90	0.94	0.79	0.84	0.87	1.08	1.10	1.12	1.08	1.07	1.03
3250	1.06	0.99	1.11	0.91	1.02	1.14	1.06	1.06	1.05	1.09	1.09	1.11
4150	1.52	1.51	1.69	0.62	0.79	1.26	1.25	1.26	1.22	1.28	1.28	1.34
5050	1.35	1.32	1.43	0.84	0.96	1.21	1.69	1.72	1.76	1.34	1.38	1.48

Typical Performance Curves



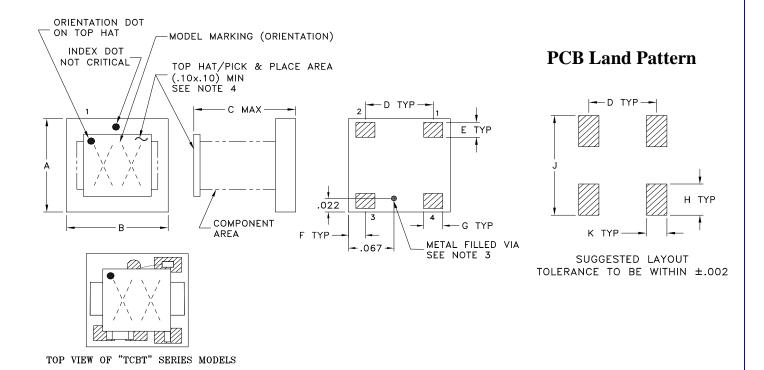






Outline Dimensions

GU1604



CASE #	A	В	C	D	E	F	G	Н	J	K	WT.GRAMS
GU1604	.150 (3.81)	.150 (3.81)	.150 (3.81)	.100 (2.54)	.030 (.76)	.025 (.64)	.028 (.71)	.050 (1.27)	.160 (4.06)	.030 (.76)	.10

Dimensions are in inches (mm). Tolerances: 2 Pl. ± .01; 3 Pl. ± .005

Notes:

- 1. Open style, Ceramic Base.
- 2. Termination finish: Silver Palladium or Gold Over Nickel based on stock availability.
- 3. Must be isolated from external conductors on mounting surface. Suggested solder mask area is .025 x .025. At Mini-Circuits option via may be removed.
- 4. Top-Hat total thickness: .013 inches MAX.
- 5. Orientation Dot on Top Hat corresponds to Pin #1.





P.O. Box 350166, Brooklyn, New York 11235-0003 (718) 934-4500 Fax (718) 332-4661 For detailed performance specs & shopping online see Mini-Circuits web site



RF/IF MICROWAVE COMPONENTS

Tape & Reel Packaging TR-F77

DEVICE ORIENTATION IN T&R INDEX DEVICE CAVITY PITCH TAPE WIDTH

INDEX -

Note: The location and shape of the metallization may differ

Note: The shape of the pocket may differ

Applicable Case Styles

DIRECTION OF FEED

GU1604, GU1804, GU2644, TT1618-2 TAPE WIDTH

DEVICE ORIENTATION IN T&R

DEVICE CAVITY

Applicable Case Styles

DIRECTION OF FEED

MZ4532C, NM1812C, NM1812C-1, NM1812C-2, NM1812C-3, NM1812C-5, NM1812C-6, NM3237

Tape Width, mm	Device Cavity Pitch, mm	Reel Size, inches	Devices pe	er Reel
12	8	7	Small quantity standards (see note)	20 50 100 200 500 1000
		13	Standard	2000

Note: Please Consult individual model data sheet to determine device per reel availability.

Mini-Circuits carrier tape materials provide protection from ESD (Electro-Static Discharge) during handling and transportation. Tapes are static dissipative and comply with industry standards EIA-481/EIA-541.

Go to: www.minicircuits.com/pages/pdfs/tape.pdf



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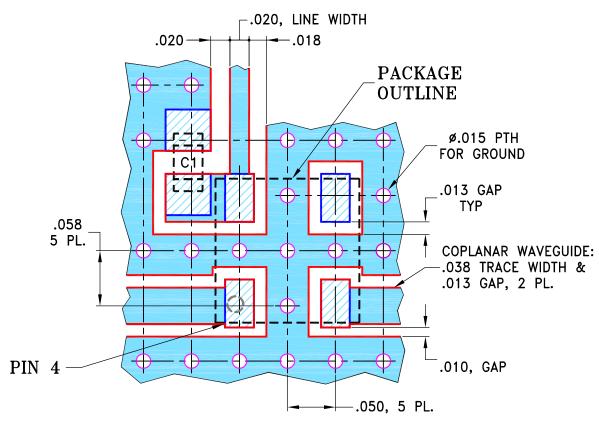
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		REVISIONS			
REV	ECN No.	DESCRIPTION	DATE	DR	AUTH
В	M102713	ADDED "WITH SMOBC"	01/12/06	GF	IL
C	M103775	.010 uF WAS .010 mF	03/01/06	MMG	DJ
D	M154947	CHANGED PIN1 & PIN CONNECTION	02/03/16	ITG	DJ
E	M167305	CHANGED CASE STYLE & PIN CONNECT.	04/18/18	ITG	IG

SUGGESTED MOUNTING CONFIGURATION FOR GU1604 CASE STYLE, "04BT01" PIN CONNECTION



CAPACITOR C1: .010 uF, 0603 SIZE

NOTES:

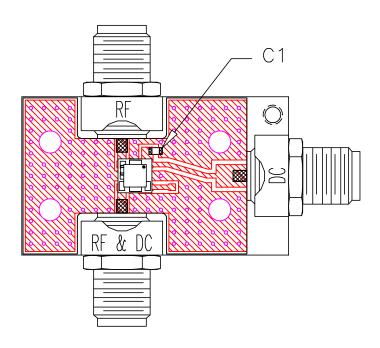
- 1. COPLANAR WAVEGUIDE PARAMETERS ARE SHOWN FOR ROGERS RO4350B WITH DIELECTRIC THICKNESS 0.020±0.0015; COPPER: 1/2 OZ. EACH SIDE. FOR OTHER MATERIALS TRACE WIDTH AND GAP MAY NEED TO BE MODIFIED.
- 2. BOTTOM SIDE OF THE PCB IS CONTINUOUS GROUND PLANE.

DENOTES PCB COPPER LAYOUT WITH SMOBC (SOLDER MASK OVER BARE COPPER).

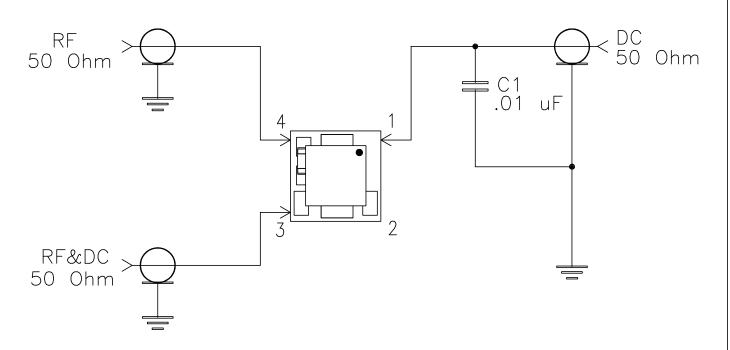
DENOTES COPPER LAND PATTERN FREE OF SOLDER MASK.

UNLESS OTHERWISE SPECIFIED		INITIALS	DATE	l —	¬ ъ	. ~		• 4 (R)			
DIMENSIONS ARE IN INCHES	DRAWN	AV	10/13/03]	Mini	ı — C	ircu	${ m its}$	13 Neptu	ne Aven	ue
TOLERANCES ON: 2 PL DECIMALS ±	CHECKED	IL	10/23/03		Τ				Бгоокіуп	NI IIZ	30
3 PL DECIMALS ± .005	APPROVED	DJ	10/23/03								
FRACTIONS ±] PI	. 04BT0	1. GU	J1604.	TCB	г. тв	-26	8
Mini−	Circuits ®				,	,	,		,		
THIS DOCUMENT AND ITS CONTENTS A EXCEPT FOR USE EXPRESSLY GRANTED					T					т —	
AND THE UNITED STATES GOVERNMENT				SIZE	CODE IDENT	DRAWING				REV:	
DESIGN, USE , MANUFACTURING AND F THESE CONTENTS SHALL NOT BE USED	EPRODUCTION R	RIGHTS THERETO. OR DISCLOSED TO A	NY OUTSIDE	A	15542		98-PL	-146		F	3
PARTY, IN WHOLE OR IN PART, WITHOU	UI WRIITEN PER	MISSION OF MINI-C	IKCUITS.	FILE: C	98PL146	SCALE:	10:1	SHEET:	1	ΛF	1
	ASHEETA1.D	WG REV:A DA	TE:01/12/95	2	10PL140		10:1		1	Ur	1

Evaluation Board and Circuit



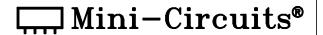
TB-268



Schematic Diagram

Notes:

- 1. SMA Female connectors.
- 2. PCB Material: Rogers RO4350 or equivalent, Dielectric Constant=3.5, Thickness=.020 inch.





Environmental Specifications

ENV02T1

All Mini-Circuits products are manufactured under exacting quality assurance and control standards, and are capable of meeting published specifications after being subjected to any or all of the following physical and environmental test.

Specification	Test/Inspection Condition	Reference/Spec
Operating Temperature	-40° to 85°C Ambient Environment	Individual Model Data Sheet
Storage Temperature	-55° to 100° C Ambient Environment	Individual Model Data Sheet
Humidity	90 to 95% RH, 240 hours, 50°C	MIL-STD-202, Method 103, Condition A, Except 50°C and end-point electrical test done within 12 hours
Thermal Shock	-55° to 100°C, 100 cycles	MIL-STD-202, Method 107, Condition A-3, except +100°C
Solder Reflow Heat	Sn-Pb Eutetic Process: 225°C peak Pb-Free Process 245° - 250°C peak	J-STD-020, Table 4-1, 4-2 and 5-2, Figure 5-1
Solderability	10X Magnification	J-STD-002, 95% Coverage
Vibration (High Frequency)	20g peak, 10-2000 Hz, 12 times in each of three perpendicular directions (total 36)	MIL-STD-202, Method 204, Condition D
Mechanical Shock	50g, 11 ms, 1/2-sine, 18 shocks: 3 each direction, each of 3 axes	MIL-STD-202, Method 213, Condition A
Marking Resistance to Solvents	Isopropyl alcohol + mineral spirits at 25°C; terpene defluxer at 25°C; distilled water + proylene glycol monomethyl ether + monoethanolamine at 63°C to 70°C	MIL-STD-202, Method 215

ENV02T1 Rev: B

02/25/11

M130240 File: ENV02T1.pdf

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